



# VOIDLESS HERMETICALLY SEALED SWITCHING DIODES

Qualified per MIL-PRF-19500/578

Qualified Levels: JAN, JANTX, JANTXV and JANS

## DESCRIPTION

This popular surface mount equivalent JEDEC registered switching/signal diodes are military qualified and available with internal metallurgical bonded construction. These small low capacitance diodes with very fast switching speeds are hermetically sealed and bonded into a "D-5D" package. They may be used in a variety of fast switching applications including computers and peripheral equipment such as magnetic cores, thin-film memories, plated-wire memories, as well as decoding or encoding applications, etc. Microsemi also offers a variety of other switching/signal diodes.

Important: For the latest information, visit our website http://www.microsemi.com.

#### **FEATURES**

- JEDEC registered surface mount equivalents of 1N6638, 1N6642, and 1N6643.
- Ultra fast recovery time.
- Very low capacitance.
- Metallurgically bonded.
- Non-cavity glass package.
- JAN, JANTX, JANTXV and JANS qualifications are available per MIL-PRF-19500/578.
- Replacements for 1N4148UR, 1N4148UR-1, 1N4150UR-1, and 1N914UR.
- RoHS compliant devices available (commercial grade only).

## **APPLICATIONS / BENEFITS**

- Small size for high density mounting (see package illustration).
- Ideal for:

High frequency data lines

RS-232 & RS-422 Interface Networks

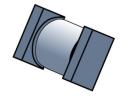
Ethernet: 10 Base T Switching core drivers

LAN Computers

# MAXIMUM RATINGS @ T<sub>A</sub> = +25 °C unless otherwise noted.

Parameters/Test Conditions	Symbol	Value	Unit	
Junction and Storage Temp	T <sub>J</sub> and T <sub>STG</sub>	-65 to +175	°C	
Thermal Resistance Junction-to-End	$R_{\Theta JEC}$	40	°C/W	
Thermal Resistance Junction-to-Amb	R <sub>OJA</sub>	250	°C/W	
Peak Forward Surge Current @ T <sub>A</sub> = (Test pulse = 8.3 ms, half-sine wave.)	I <sub>FSM</sub>	2.5	Α	
Average Rectified Forward Current @ (Derate at 4.6 mA/°C Above T <sub>EC</sub> = + 1	lo	300	mA	
Breakdown Voltage: 1N6638US 1N6642US 1N6643US		V <sub>BR</sub>	150 100 75	V
Working Peak Reverse Voltage: 1N6638US 1N6642US		V <sub>RWM</sub>	125 75	V
	1N6643US		50	

NOTES: 1. T<sub>A</sub> = +75 °C on printed circuit board (PCB), PCB = FR4 - .0625 inch (1.59 mm) 1-layer 1-Oz Cu, horizontal, in still air; pads for US = .061 inch (1.55 mm) x .105 inch (2.67 mm); R<sub>OJA</sub> with a defined PCB thermal resistance condition included, is measured at I<sub>O</sub> = 300 mA.



"D" SQ-MELF (D-5D) Package

Also available in:

"D" Package
(axial-leaded)
1N6638 42 43

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## **MECHANICAL and PACKAGING**

- CASE: Voidless hermetically sealed hard glass.
- TERMINALS: Tin-Lead plate with >3% Lead. Solder dip is available upon request.
- MARKING: Body painted and alpha numeric.
- POLARITY: Cathode indicated by band.
- Tape & Reel option: Standard per EIA-481-1-A with 12 mm tape. Consult factory for quantities.
- See <u>Package Dimensions</u> on last page.

#### PART NOMENCLATURE JAN 1N6638 US (e3)**RoHS Compliance Reliability Level** JAN = JAN Level e3 = RoHS compliant (available JANTX = JANTX Level on commercial grade only) JANTXV = JANTXV Level Blank = non-RoHS compliant JANS = JANS Level Blank = commercial **Surface Mount Package** JEDEC type number See Electrical Characteristics

SYMBOLS & DEFINITIONS					
Symbol	Definition				
$V_{BR}$	Minimum Breakdown Voltage: The minimum voltage the device will exhibit at a specified current.				
$V_{RWM}$	Working Peak Reverse Voltage: The maximum peak voltage that can be applied over the operating temperature range.				
$V_{F}$	Maximum Forward Voltage: The maximum forward voltage the device will exhibit at a specified current.				
I <sub>R</sub>	Maximum Reverse Current: The maximum reverse (leakage) current that will flow at the specified voltage and temperature.				
С	Capacitance: The capacitance in pF at a frequency of 1 MHz and specified voltage.				
t <sub>rr</sub>	Reverse Recovery Time: The time interval between the instant the current passes through zero when changing from the forward direction to the reverse direction and a specified recovery decay point after a peak reverse current is reached.				

## **ELECTRICAL CHARACTERISTICS** @ 25°C unless otherwise noted.

TYPE NUMBER	MAXIMUM FORWARD VOLTAGE V <sub>F</sub> @ I <sub>F</sub>		MAXIMUM DC REVERSE CURRENT			REVERSE RECOVERY TIME t <sub>rr</sub> (Note 1)	MAXIMUM FORWARD RECOVERY VOLTAGE AND TIME I <sub>F</sub> =200mA, t,=1ns		MAXIMUM JUNCTION CAPACITANCE f = 1 MHz Vsig = 50 mV		
			V <sub>R</sub> = 20 V	V <sub>R</sub> =V <sub>RWM</sub>	I <sub>R3</sub> V <sub>R</sub> =20 V T <sub>A</sub> = +150 °C	I <sub>R4</sub> V <sub>R</sub> =V <sub>RWM</sub> T <sub>A</sub> = +150 °C		V <sub>FRM</sub>	t <sub>fr</sub>	ν <sub>R</sub> =0 V	-p) V <sub>R</sub> =1.5 V
	V @ mA	V @ mA	nA	nA	μА	μА	ns	٧	ns	pf	pf
1N6638US	0.8 V @ 10 mA	1.1 V @ 200 mA	35	500	50	100	4.5	5.0	20	2.5	2.0
1N6642US	0.8 V @ 10 mA	1.2 V @ 100 mA	25	500	50	100	5.0	5.0	20	5.0	2.8
1N6643US	0.8 V @ 10 mA	1.2 V @ 100 mA	50	500	75	100	6.0	5.0	20	5.0	2.8

NOTE: 1. Reverse Recovery Time Test Conditions – I<sub>F</sub>=I<sub>R</sub>=10 mA, I<sub>R(REC)</sub> = 1.0 mA, C=3 pF, R<sub>L</sub> = 100 ohms.



## **GRAPHS**

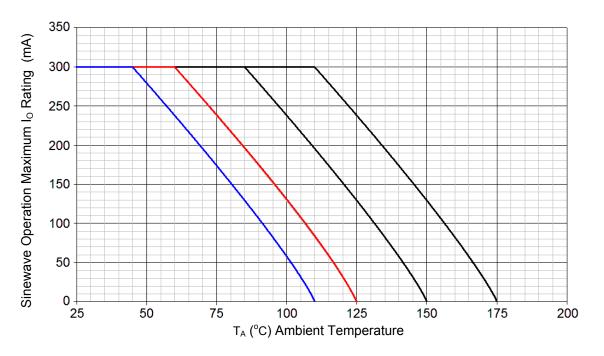


FIGURE 1
Temperature – Current Derating

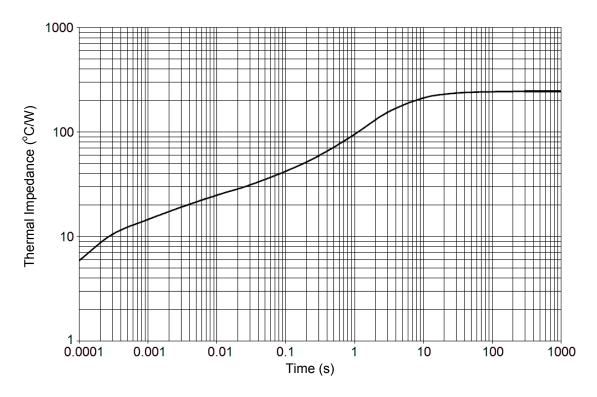


FIGURE 2 Maximum Thermal Impedance at  $T_A = 55$  °C



## **GRAPHS** (continued)

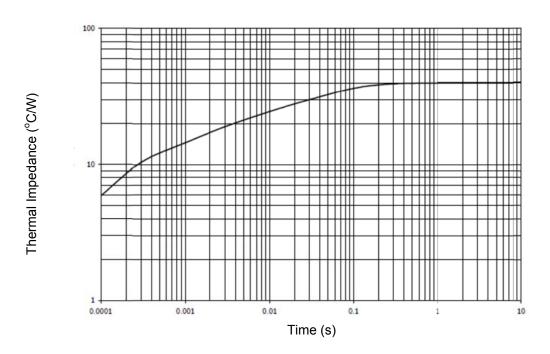
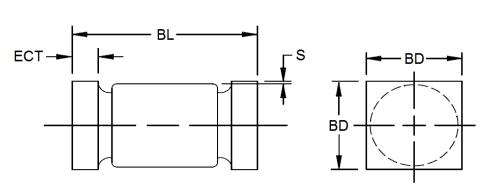


FIGURE 3 Maximum Thermal Impedance at  $T_{EC}$  = 25  $^{\circ}C$ 



## **PACKAGE DIMENSIONS**

## D-5D



	IN	СН	MILLIMETERS			
DIM	MIN	MAX	MIN	MAX		
BD	<b>BD</b> 0.070 0.085		1.78	2.16		
ECT	0.019	0.028	0.48	0.71		
BL	0.165	0.195	4.19	4.95		
s	0.003	3 MIN.	0.08 MIN.			

## **NOTES:**

- 1. Dimensions are in inches. Millimeters are given for general information only.
- 2. Dimensions are pre-solder dip.
- U-suffix parts are structurally identical to the US-suffix parts.
   In accordance with ASME Y14.5M, diameters are equivalent to Φx symbology.

# **Mouser Electronics**

**Authorized Distributor** 

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# Microchip:

<u>JANS1N6638U</u> <u>JANTX1N6643U</u> <u>JAN1N6638U</u> <u>JANTXV1N6638U</u> <u>JANTX1N6638US</u> <u>JAN1N6643US</u> <u>JANTX1N6638US</u> <u>JANTX1N6638US</u> <u>JANTX1N6638US</u> <u>JANTX1N6638US</u> <u>JANTX1N6638US</u> <u>JANTX1N6638US</u> <u>JANTX1N6638US</u> <u>JANTXV1N6642US</u> <u>JANTXX</u>